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PATENT APPLICATION
Mo-6366
MD-01-34-KU

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#6

APPLICATION OF

JACK C. CHAN ET AL

SERIAL NUMBER: 09/865,322

FILED: MAY 25, 2001

TITLE: A PROCESS FOR MAKING
BLOOM-FREE THERMO-
PLASTIC POLYURETHANE
COMPOSITIONS

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) GROUP NO.: 1711
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) EXAMINER: RACHEL F. GORR
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ORIGINALLY FILED

DECLARATION UNDER 37 CFR 1.132

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

I, Jack C. Chan, a U.S. citizen do hereby declare:

That my educational background includes graduate studies in Chemistry at the University of Texas at Austin and that I was conferred the degree of Ph.D. in Chemistry from this University, and

That I am an employee of Bayer Corporation, the assignee of the captioned patent application (Application), and have for eight years been engaged in Research and Development at Bayer in the field of thermoplastic polyurethane (TPU), and

That I am an inventor named in the Application, and

That I have read the Office Action issued March 13, 2002 in the prosecution of the Application and the art cited therein, and

That the TPU compositions that were evaluated in the course of work leading to the claimed invention were prepared in accordance with my direction and under my supervision; and

That the compositional makeup of the TPU referred to in Examples 1, 2 and 3 (page 7 lines 1-14 of the Application) included stearic acid amide in an amount effective to impart mold release quality to the composition.

That the compositional makeup of the TPU referred to in Examples 2 and 3 further included stearyl alcohol.

The undersigned Declarant declares further that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States code and that such willful false statements may jeopardize the validity of pending Application Serial Number 09/865,322 or any patent issuing thereon.

Signed at Irvine, CA this 9th day of July, 2002.

Jack C. Cha
Inventor name